

SY89859U

Precision Low-Power 8:1 MUX with Internal Termination and 1:2 LVPECL Fanout Buffer

General Description

The SY89859U is a low jitter, low-power, high-speed 8:1 multiplexer with a 1:2 differential fanout buffer optimized for precision telecom and enterprise server distribution applications. The SY89859U distributes clock frequencies from DC to >2.5GHz, and data rates to 2.5Gbps guaranteed over temperature and voltage.

The SY89859U differential input includes Micrel's unique, 3-pin input termination architecture that directly interfaces to any differential signal (AC- or DC-coupled) as small as 100mV (200mVpp) without level shifting or termination resistor networks in the signal path. The outputs are 800mV, 100K-compatible LVPECL with extremely fast rise/fall time guaranteed to be less than 180ps.

The SY89859U features a patent-pending isolation design that significantly improves on channel-tochannel crosstalk-induced jitter performance.

The SY89859U operates from a 2.5V \pm 5% or 3.3V \pm 10% supply and is guaranteed over the full industrial temperature range of -40°C to +85°C. The SY89859U is part of Micrel's high-speed, Precision Edge[®] product line.

All support documentation can be found on Micrel's web site at: <u>www.micrel.com</u>.



Features

- Selects between 1 of 8 inputs, and provides 2 precision, low skew 100K-compatible LVPECL output copies
- Low power: 150mW typ. (2.5V)
- Guaranteed AC performance over temperature and voltage:
 - DC to >2.5Gbps
 - DC to >2.5GHz
 - <690ps propagation delay
 - <180ps t_r/t_f time
 - <20ps skew (output-to-output)
- Unique, patent-pending channel-to-channel isolation design provides superior crosstalk performance
- Ultra-low jitter design:
 - <1ps_{RMS} random jitter
 - <10ps_{PP} deterministic jitter
 - <10ps_{PP} total jitter (clock)
 - <1ps_{RMS} cycle-to-cycle jitter
 - <0.7ps_{RMS} crosstalk-induced jitter
- Unique, patented input termination and VT pin accepts DC- and AC-coupled inputs (CML, PECL, LVDS)
- Power supply 2.5V ±5% or 3.3V ±10%
- -40°C to +85°C industrial temperature range
- Available in 44-pin (7mm x 7mm) MLF[®] package

Applications

- Data communication systems
- All SONET/SDH data/clock applications
- All Fibre Channel applications
- All Gigabit Ethernet applications

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Functional Block Diagram



Ordering Information⁽¹⁾

| Part Number | Package Type | Operating Range | Package Marking | Lead Finish |
|-----------------------------|--------------|--------------------|--|-------------------|
| SY89859UMG | MLF-44 | Industrial | SY89859U with Pb-Free bar-line indicator | NiPdAu Pb-Free |
| SY89859UMGTR ⁽²⁾ | MLF-44 | Industrial | SY89859U with Pb-Free bar-line indicator | NiPdAu Pb-Free |

Notes:

1. Contact factory for die availability. Dice are guaranteed at $T_A = 25^{\circ}C$, DC Electricals only.

2. Tape and Reel.

Pin Configuration



Truth Table

| SEL2 | SEL1 | SEL0 | Q | /Q |
|------|------|------|-----|------|
| L | L | L | IN0 | /IN0 |
| L | L | Н | IN1 | /IN1 |
| L | Н | L | IN2 | /IN2 |
| L | Н | Н | IN3 | /IN3 |
| Н | L | L | IN4 | /IN4 |
| Н | L | Н | IN5 | /IN5 |
| Н | Н | L | IN6 | /IN6 |
| Н | Н | Н | IN7 | /IN7 |

Pin Description

| Pin Number | Pin Name | Pin Function |
|---|--|--|
| 20, 18 16, 14 13, 11 9, 7 5, 3 1, 43 42, 40 38, 36 | IN0, /IN0 IN1, /IN1 IN2, /IN2 IN3, /IN3 IN4, /IN4 IN5, /IN5 IN6, /IN6 IN7, /IN7 | Differential Inputs: These input pairs are the differential signal inputs to the device. Inputs accept AC- or DC-coupled signals as small as 100mV (200mVpp). Each pin of a pair internally terminates to a VT pin through 50Ω . Note that these inputs will default to an indeterminate state if left open. Please refer to the "Input Interface Applications" section for more details. |
| 19, 15 12, 8 4, 44 41, 37 | VT0, VT1 VT2, VT3 VT4, VT5 VT6, VT7 | Input Termination Center-Tap: Each side of the differential input pair terminates to a VT pin. The VT pins provide a center-tap to a termination network for maximum interface flexibility. See "Input Interface Applications" section for more details. For a CML or LVDS inputs, the VT pin is left floating. |
| 17 10 2 39 | VREF-AC0 VREF-AC1 VREF-AC2 VREF-AC3 | Reference Voltage: These outputs bias to V_{CC} -1.2V. They are used when AC coupling the inputs (IN, /IN). For AC-coupled applications, connect VREF-AC to the VT pin and bypass with a 0.01µF low ESR capacitor to VCC. See "Input Interface Applications" section for more details. |
| 21 22 35 | SEL0 SEL1 SEL2 | The single-ended TTL/CMOS-compatible inputs select the inputs to the multiplexer. Note that this input is internally connected to a $25k\Omega$ pull-up resistor and will default to a logic HIGH state if left open. The threshold voltage is V _{TH} = V _{CC} /2. |
| 24, 27, 29, 32 | VCC | Positive Power Supply. Bypass with 0.1μ F 0.01μ F low ESR capacitors and place as close to each VCC pin as possible. |
| 25, 26 30, 31 | Q0, /Q0 Q1, /Q1 | Differential Outputs: These 100K-compatible LVPECL output pairs are the outputs of the device. Unused output pairs may be left open. Each output is designed to drive 800mV into 50Ω terminated to V _{CC} -2V. |
| 23, 28, 33 | GND Exposed Pad | Ground. GND and exposed pad must both be connected to the same ground plane. |

Absolute Maximum Ratings⁽¹⁾

| Supply Voltage (V _{CC}) –0.5V to +4.0V Input Voltage |
|---|
| SEL0, SEL1, SEL2 –0.5V to V _{cc} |
| IN0, /IN0, IN1, /IN1,/IN7, /IN70.5V to V _{CC} |
| LVPECL Output Current (Iout) |
| Continuous±50mA |
| Surge±100mA |
| Termination Current |
| Source or sink current |
| VT0, VT1, VT2,VT7±100mA |
| Input Current |
| Source or sink current |
| IN0, /IN0, IN1, /IN1,IN7, /IN7 ±50mA |
| VREF Output Current |
| VREF-AC0, VREF-AC1, VREF-AC3 ±2mA |
| Lead Temperature (soldering, 20 sec.)+260°C |
| Storage Temperature (T _s)–65°C to 150°C |
| |

Operating Ratings⁽²⁾

| Supply Voltage (V _{CC}) | +2.375V to +2.625V |
|--|--------------------|
| | +3.0V to +3.6V |
| Ambient Temperature (T _A) | –40°C to +85°C |
| Ambient Temperature (T _A) Package Thermal Resistance ⁽³⁾ | |
| MLF [®] (θ _{JA}) | |
| Still-Air | 24°C/W |
| MLF [®] (ψ _{JB}) | |
| Junction-to-Board | 12°C/W |

DC Electrical Characteristics⁽⁴⁾

 $T_A = -40^{\circ}C$ to +85°C, unless otherwise stated.

| Symbol | Parameter | Condition | Min | Тур | Max | Units |
|-----------------------------|--|-------------------------------|----------------------|----------------------|----------------------|-------|
| V _{CC} | Power Supply | | 2.375 | 2.5 | 2.625 | V |
| | | | 3.0 | 3.3 | 3.6 | V |
| I _{CC} | Power Supply Current | No load, max. V _{CC} | | 60 | 85 | mA |
| R _{IN} | Input Resistance (IN-to-V _T) | | 45 | 50 | 55 | Ω |
| $R_{\text{DIFF}_{IN}}$ | Differential Input Resistance (IN-to-/IN) | | 90 | 100 | 110 | Ω |
| V _{IH} | Input High Voltage (IN, /IN) | Note 5 | V _{CC} -1.6 | | Vcc | V |
| VIL | Input Low Voltage (IN, /IN) | | 0 | | V _{IH} —0.1 | V |
| V _{IN} | Input Voltage Swing (IN, /IN) | See Figure 1a. | 0.1 | | 1.7 | V |
| $V_{\text{DIFF}_\text{IN}}$ | Differential Input Voltage Swing IN-to-/IN | See Figure 1b. | 0.2 | | | V |
| V_{T_IN} | IN-to-V _T (IN, /IN) | | | | 1.28 | V |
| V _{REF-AC} | Output Reference Voltage | | V _{CC} -1.3 | V _{cc} -1.2 | V _{cc} -1.1 | V |

Notes:

1. Permanent device damage may occur if absolute maximum ratings are exceeded. This is a stress rating only and functional operation is not implied at conditions other than those detailed in the operational sections of this data sheet. Exposure to absolute maximum ratings conditions for extended periods may affect device reliability.

2. The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.

3. Package thermal resistance assumes exposed pad is soldered (or equivalent) to the devices most negative potential on the PCB. θ_{JA} and Ψ_{JB} values are determined for a 4-layer board in still-air, unless otherwise stated.

4. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.

5. V_{IH} (min) not lower than 1.2V.

100K LVPECL Output DC Electrical Characteristics⁽⁶⁾

 V_{CC} = +2.5V ±5% or 3.3V ±10%, R_L = 50 Ω to V_{CC} -2V; T_A = -40°C to +85°C, unless otherwise stated.

| Symbol | Parameter | Condition | Min | Тур | Max | Units |
|-----------------------|-----------------------------------|----------------|------------------------|------|------------------------|-------|
| V _{OH} | Output HIGH Voltage (Q, /Q) | | V _{CC} -1.145 | | V _{CC} -0.895 | V |
| V _{OL} | Output LOW Voltage (Q, /Q) | | V _{CC} -1.945 | | V _{CC} -1.695 | V |
| V _{OUT} | Output Differential Swing | See Figure 1a. | 550 | 800 | | mV |
| V _{DIFF_OUT} | Differential Output Voltage Swing | See Figure 1b. | 1100 | 1600 | | mV |

LVTTL/CMOS DC Electrical Characteristics⁽⁶⁾

 V_{CC} = +2.5V ±5% or 3.3V ±10%; T_A = -40°C to +85°C, unless otherwise stated.

| Symbol | Parameter | Condition | Min | Тур | Max | Units |
|-----------------|--------------------|---|------|-----|-----|-------|
| V _{IH} | Input HIGH Voltage | | 2.0 | | | V |
| V _{IL} | Input LOW Voltage | | | | 0.8 | V |
| IIH | Input HIGH Current | I _{IH} @ V _{IN} = V _{CC} | -125 | | 40 | μA |
| IIL | Input LOW Current | $I_{IL} @ V_{IN} = 0.5V$ | -300 | | | μA |

Note:

6. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.

AC Electrical Characteristics⁽⁷⁾

 V_{CC} = +2.5V ±5% or 3.3V ±10%; V_{IN} ≥100mV (200mVpp); R_L = 50Ω to V_{CC} -2V; T_A = -40°C to +85°C, unless otherwise stated.

| Symbol | Parameter | Condition | Min | Тур | Max | Units |
|--------------------------------|---|-----------------------|-----|-----|-----|-------------------|
| 1 | Maximum Operating Frequency | | 2.5 | | | Gbps |
| f _{MAX} | | | 2.5 | 3.5 | | GHz |
| | Differential Propagation Delay | | | | | |
| t _{pd} | IN-to-Q | | 360 | 475 | 640 | ps |
| | SEL-to-Q | | 200 | 600 | 850 | ps |
| t _{pd} | Differential Propagation Delay | IN-to-Q | | 300 | | fs/°C |
| Tempco | Temperature Coefficient | SEL-to-Q | | 400 | | IS/ C |
| | Output-to-Output Skew | Note 8 | 5 | | 20 | ps |
| tskew | Part-to-Part Skew | Note 9 | | | 200 | ps |
| | Data | | | | | |
| | Random Jitter (RJ) | Note 10 | | | 1 | ps _{RMS} |
| | Deterministic Jitter (DJ) | Note 11 | | | 10 | ps _{PP} |
| t JITTER | Clock | | | | | |
| | Cycle-to-Cycle Jitter | Note 12 | | | 1 | ps _{RMS} |
| | Total Jitter (TJ) | Note 13 | | | 10 | pspp |
| | Adjacent Channel Crosstalk-induced Jitter | Note 14 | | | 0.7 | ps _{RMS} |
| t _{r,} t _f | Output Rise/Fall Time (20% to 80%) | At full output swing. | 50 | 110 | 180 | ps |

Notes:

7. High-frequency AC-parameters are guaranteed by design and characterization.

8. Output-to-output skew is measured between two different outputs under identical input transitions.

9. Part-to-part skew is defined for two parts with identical power supply voltages at the same temperature and with no skew of the edges at the respective inputs.

10. Random jitter is measured with a K28.7 character pattern, measured at ${<}f_{\text{MAX}}$

- 11. Deterministic jitter is measured at 2.5Gbps with both K28.5 and 2^{23} –1 PRBS pattern.
- 12. Cycle-to-cycle jitter definition: the variation of periods between adjacent cycles, T_n T_{n-1} where T is the time between rising edges of the output signal.
- 13. Total jitter definition: with an ideal clock input of frequency <f_{MAX}, no more than one output edge in 10¹² output edges will deviate by more than the specified peak-to-peak jitter value.
- 14. Crosstalk-induced jitter is defined as the added jitter that results from signals applied to two adjacent channels. It is measured at the output while applying two similar, differential clock frequencies that are asynchronous with respect to each other at the inputs.

Single-Ended and Differential Swings



Figure 1a. Single-Ended Voltage Swing



Figure 1b. Differential Voltage Swing

Typical Operating Characteristics

 V_{CC} = 3.3V, GND = 0, V_{IN} = 100mV (200mVpp), R_L = 50 Ω to V_{CC} -2V; T_A = 25°C, unless otherwise stated.



Functional Characteristics

 V_{CC} = 3.3V, GND = 0, V_{IN} = 100mV (200mVpp), R_L = 50 Ω to V_{CC} -2V; T_A = 25°C, unless otherwise stated.



Input and Output Stages



Figure 2a. Simplified Differential Input Stage



Figure 2b. Simplified LVPECL Output Stage

Input Interface Applications





Figure 3d. CML Interface

(AC-Coupled)

LVPECL Output Interface Applications

LVPECL has high input impedance, very low output (open emitter) impedance, and small signal swing which result in low EMI. LVPECL is ideal for driving 50 Ω - and 100 Ω -controlled impedance transmission lines. There are several techniques for terminating

the LVPECL output including: Parallel Termination-Thevenin Equivalent, Parallel Termination (3-Resistor), and AC-Coupled Termination. Unused output pairs may be left floating. However, singleended outputs must be terminated, or balanced.







Note: For 2.5V system, $Rb = 19\Omega$.

Note:

For 2.5V system, R1 = 250Ω , R2 = 62.5Ω .

Related Product and Support Documentation

| Part Number | Function | Data Sheet Link |
|---------------|--|--|
| SY58037U | Ultra Precision 8:1 MUX with Internal Termination and 1:2 CML Fanout Buffer | http://www.micrel.com/product-info/products/sy58037u.shtml |
| SY58038U | Ultra Precision 8:1 MUX with Internal Termination and 1:2 LVPECL Fanout Buffer | http://www.micrel.com/product-info/products/sy58038u.shtml |
| SY58039U | Ultra Precision 8:1 MUX with Internal Termination and 1:2 400mV LVPECL Fanout Buffer | http://www.micrel.com/product-info/products/sy58039u.shtml |
| HBW Solutions | New Products and Applications | www.micrel.com/product-info/products/solutions.shtml |
| | MLF [®] Application Note | www.amkor.com/products/notes_papers/MLFAppNote.pdf |



PCB Thermal Consideration for 44-Pin MLF[™] Package (Always solder, or equivalent, the exposed pad to the PCB)

Package Notes:

- 1. Package meets Level 2 qualification.
- 2. All parts are dry-packaged before shipment.
- 3. Exposed pads must be soldered to a ground for proper thermal management.

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